



Dr. David E. Lee

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David E. Lee is a program manager and space vehicle systems engineer at Northrop Grumman Aerospace Systems in Redondo Beach, California. Currently, he is the manager for the Integrated Concept Development Facility and is program manager for multiple contracts. As principal investigator, he leads the FSPOT-X (Full Spectrum Power for Optical/Thermal Exergy) Project funded by the Department of Energy's ARPA-E FOCUS Program.

He is the area lead for both thermal power development as well as space tether technologies and systems within Aerospace Systems.

Previously, as a project manufacturing engineer, he supervised production of spacecraft structural components and assembly of space structures. He has developed algorithms and software for real-time simulation of operational radar environments and for modular and virtual manufacturing process control.

His research interests and technical foci include: next generation systems modeling, multi-int data fusion, autonomous systems operations, scalable space architectures, electrodynamic tethers, solar thermal energy production, integrated power and water generation.

As an educator, Dr. Lee is currently the lead instructor for the Spacecraft Systems Design and Analysis as well as the Space Mission Systems Engineering courses offered through UCLA Extension's Astronautical Engineering Certificate Program. He has taught classes on Manufacturing Processes to undergraduate and graduates at UCLA's Mechanical and Aerospace Engineering Department.

Dr. Lee completed his dissertation in Mechanical Engineering through the Integrated Manufacturing Engineering Program for Advanced Transportation Systems at UCLA. He received his B.A. in Mathematics and M.S. in Manufacturing Engineering all from UCLA. He is a Fellow of the American Society of Mechanical Engineers and senior member of the American Institute of Aeronautics and Astronautics. In addition he is a member of ACM, IEEE, INCOSE and NDIA.